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L18	0	((test same pattern same wafer)	US-PGPUB;	OR	ON	2005/10/16 12:23
		and configur\$4 and adjust\$4 and				
		(layout or laid adj out) and (region	USOCR;			
		or area) and sensitive and	EPO; JPO;			
		fabricat\$4).CLM.	DERWENT;			
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1. Sensor for monitoring the rinsing of patterned wafers

Jun Yan; Seif, D.; Raghavan, S.; Vermeire, B.; Barnaby, H.J.; Peterson, T.; Sh Semiconductor Manufacturing, IEEE Transactions on

Volume 17, Issue 4, Nov. 2004 Page(s):531 - 537 Digital Object Identifier 10.1109/TSM.2004.837001

AbstractPlus | References | Full Text: PDF(1144 KB) | IEEE JNL

2. Large deflection micromechanical scanning mirrors for linear scans and generation

Schenk, H.; Durr, P.; Haase, T.; Kunze, D.; Sobe, U.; Lakner, H.; Kuck, H.; Selected Topics in Quantum Electronics, IEEE Journal of Volume 6, Issue 5, Sept.-Oct. 2000 Page(s):715 - 722

Digital Object Identifier 10.1109/2944.892609

AbstractPlus | References | Full Text: PDF(432 KB) | IEEE JNL

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L1	322	(test same pattern same fabricat\$4 same wafer) and configur\$4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/16 10:45
L2	88	(test same pattern same fabricat\$4 same wafer) and configur\$4 and layout and device	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/16 10:45
L3	5	(test same pattern same fabricat\$4 same wafer same configur\$4) and layout	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/16 10:45
L4	58	(pattern same fabricat\$4 same wafer same configur\$4) and correla\$4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/16 10:45
L5	3	((test near4 pattern) same fabricat\$4 same configur\$4) and correla\$4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/16 10:45
L6	27	((test near4 pattern) same configur\$4) and correla\$4 and fabricat\$4 and layout	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/16 10:45
L7	249	((test near4 pattern) same configur\$4) and correla\$4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/16 11:42
L8	118	((test near4 pattern) same configur\$4) and adjust\$4 and (layout or laid adj out)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/16 11:43

L9	97	((test near4 pattern) same configur\$4) and adjust\$4 and (layout or laid adj out) and (region or area)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/16 11:44
L10	8	((test near4 pattern) same configur\$4) and adjust\$4 and (layout or laid adj out) and (region or area) and "716"/\$.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/16 11:44
L11	5	((test near4 pattern) same configur\$4) and adjust\$4 and (layout or laid adj out) and (region or area) and fabricat\$4 and "716"/\$.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/16 12:05
L12	16	(test same pattern same wafer) and configur\$4 and adjust\$4 and (layout or laid adj out) and (region or area) and fabricat\$4 and "716"/\$.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/16 12:06
L13	222	(test same pattern same wafer) and configur\$4 and adjust\$4 and (layout or laid adj out) and (region or area) and fabricat\$4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/16 12:20
U14	28	(test same pattern same wafer) and configur\$4 and (adjust\$4 same (layout or laid adj out)) and (region or area) and fabricat\$4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/16 12:08
L16	7	((test same pattern same wafer) and configur\$4 and adjust\$4 and (layout or laid adj out) and (region or area) and fabricat\$4).CLM.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/16 12:22
L19	149	(test same pattern same wafer) and configur\$4 and adjust\$4 and (layout or laid adj out) and (region or area) and sensitive and fabricat\$4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/16 12:24

L20	7	and configur\$4 and adjust\$4 and (layout or laid adj out) and (region	USPAT; USOCR;	OR	ON	2005/10/16 12:25
		or area) and sensitive and fabricat\$4 and "716"/\$.ccls.	EPO; JPO; DERWENT; IBM_TDB			